

L Number	Hits	Search Text	DB	Time stamp
1	87663	polyimide	USPAT; US-PGPUB; JPO	2004/06/07 10:42
2	199154	solder\$3	USPAT; US-PGPUB; JPO	2004/06/07 10:43
3	1053	ubm or "under bump"	USPAT; US-PGPUB; JPO	2004/06/07 10:43
4	39341	contact near2 pad\$1	USPAT; US-PGPUB; JPO	2004/06/07 10:43
5	28379	reflow\$3	USPAT; US-PGPUB; JPO	2004/06/07 10:44
6	198288	seed\$3 or nucleat\$3	USPAT; US-PGPUB; JPO	2004/06/07 10:44
7	17886	solder\$3 same reflow\$3	USPAT; US-PGPUB; JPO	2004/06/07 10:44
8	88	(ubm or "under bump") same (seed\$3 or nucleat\$3)	USPAT; US-PGPUB; JPO	2004/06/07 10:44
9	629	solder\$3 same (ubm or "under bump")	USPAT; US-PGPUB; JPO	2004/06/07 10:44
10	25	polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump"))	USPAT; US-PGPUB; JPO	2004/06/07 10:45
11	25	reflow\$3 and (polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump"))))	USPAT; US-PGPUB; JPO	2004/06/07 10:45
21	27	polyimide and solder\$3 and (ubm or "under bump") and (contact near2 pad\$1) and reflow\$3 and (seed\$3 or nucleat\$3)	USPAT; US-PGPUB; JPO	2004/06/07 11:18
22	11	(polyimide and solder\$3 and (ubm or "under bump")) and (contact near2 pad\$1) and reflow\$3 and (seed\$3 or nucleat\$3)) not (polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump"))))	USPAT; US-PGPUB; JPO	2004/06/07 11:29
23	49	solder\$3 and (ubm or "under bump") and polyimide and reflow\$3 and (seed\$3 or nucleat\$3)	USPAT; US-PGPUB; JPO	2004/06/07 11:30
24	36	(polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump")))) ((polyimide and solder\$3 and (ubm or "under bump")) and (contact near2 pad\$1) and reflow\$3 and (seed\$3 or nucleat\$3)) not (polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump"))))	USPAT; US-PGPUB; JPO	2004/06/07 11:30
25	13	(solder\$3 and (ubm or "under bump")) and polyimide and reflow\$3 and (seed\$3 or nucleat\$3)) not ((polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump")))) ((polyimide and solder\$3 and (ubm or "under bump")) and (contact near2 pad\$1) and reflow\$3 and (seed\$3 or nucleat\$3)) not (polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump")))))	USPAT; US-PGPUB; JPO	2004/06/07 11:30
26	400	polyimide and solder\$3 and (ubm or "under bump")	USPAT; US-PGPUB; JPO	2004/06/07 11:31

27	49	((polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump")))) ((polyimide and solder\$3 and (ubm or "under bump") and (contact near2 pad\$1) and reflow\$3 and (seed\$3 or nucleat\$3)) not (polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump"))))) ((solder\$3 and (ubm or "under bump") and polyimide and reflow\$3 and (seed\$3 or nucleat\$3)) not ((polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump")))) ((polyimide and solder\$3 and (ubm or "under bump") and (contact near2 pad\$1) and reflow\$3 and (seed\$3 or nucleat\$3)) not (polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump")))))	USPAT; US-PGPUB; JPO	2004/06/07 11:31
28	351	((polyimide and solder\$3 and (ubm or "under bump")) not (((polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump")))) ((polyimide and solder\$3 and (ubm or "under bump") and (contact near2 pad\$1) and reflow\$3 and (seed\$3 or nucleat\$3)) not (polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump"))))) ((solder\$3 and (ubm or "under bump") and polyimide and reflow\$3 and (seed\$3 or nucleat\$3)) not ((polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump")))) ((polyimide and solder\$3 and (ubm or "under bump") and (contact near2 pad\$1) and reflow\$3 and (seed\$3 or nucleat\$3)) not (polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump")))))	USPAT; US-PGPUB; JPO	2004/06/07 11:31